

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D	$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
30V	13.5mΩ@10V	10A	-30V	20mΩ@-10V	-9.1A
	20mΩ@4.5V			35mΩ@4.5V	

Feature

- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance
- Surface mount package

Application

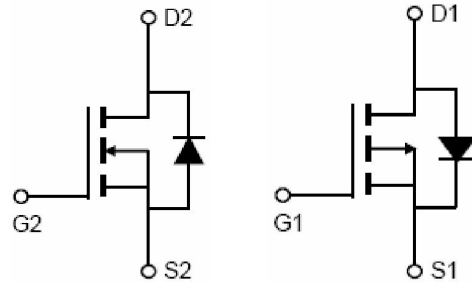
- Battery protection
- Load switch
- Power management

Package

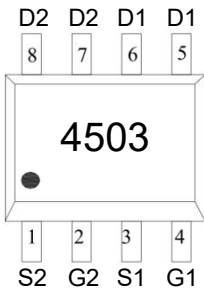


SOP-8

Circuit diagram



Marking



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	N-Channel	p-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Gate-Source Voltage	V _{GS}	±20	±20	V
Continuous Drain Current	I _D	10	-9.1	A
Pulsed Drain Current	I _{DM}	30	-30	A
Power Dissipation	P _D	2.5	2.5	W
Junction Temperature	T _J	150	150	°C
Thermal Resistance, Junction-to-Ambient ¹⁾	R _{θJA}	50	50	°C/W
Storage Temperature	T _{STG}	-55 ~ +150	-55 ~ +150	°C

N-CH Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0		3.0	V
Drain-source on-resistance ²⁾	R _{DS(on)}	V _{GS} = 10V, I _D = 10A			13.5	mΩ
		V _{GS} = 4.5V, I _D = 5A			20	mΩ
Dynamic characteristics³⁾						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		1550		pF
Output Capacitance	C _{oss}			300		
Reverse Transfer Capacitance	C _{rss}			180		
Total Gate Charge	Q _g	V _{DS} = 15V, V _{GS} = 4.5V, I _D = 10A		13		nC
Gate-Source Charge	Q _{gs}			5.5		
Gate-Drain Charge	Q _{gd}			3.5		
Turn-on delay time	t _{d(on)}	V _{DD} = 25V, V _{GS} = 10V, I _D = 1A, R _{GEN} = 6Ω		30		nS
Turn-on rise time	t _r			20		
Turn-off delay time	t _{d(off)}			100		
Turn-off fall time	t _f			80		
Source-Drain Diode characteristics						
Diode Forward voltage	V _{DS}	V _{GS} = 0V, I _S = 6A			1.2	V

P-CH Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0		-3.0	V
Drain-source on-resistance ²⁾	R _{DS(on)}	V _{GS} = -10V, I _D = -9.1A			20	mΩ
		V _{GS} = -4.5V, I _D = -5A			35	mΩ
Dynamic characteristics³⁾						
Input Capacitance	C _{iss}	V _{DS} = -15V, V _{GS} = 0V, f = 1MHz		1600		pF
Output Capacitance	C _{oss}			350		
Reverse Transfer Capacitance	C _{rss}			300		
Total Gate Charge	Q _g	V _{DS} = -15V, V _{GS} = -10V, I _D = -9.1A		30		nC
Gate-Source Charge	Q _{gs}			5.5		
Gate-Drain Charge	Q _{gd}			8		
Turn-on delay time	t _{d(on)}	V _{DD} = -15V, V _{GS} = -10V, I _D = -1A, R _{GEN} = 6Ω		10		nS
Turn-on rise time	t _r			15		
Turn-off delay time	t _{d(off)}			110		
Turn-off fall time	t _f			70		
Source-Drain Diode characteristics						
Diode Forward voltage	V _{DS}	V _{GS} = 0V, I _S = -6A			-1.2	V

Notes:

- 1) Surface Mounted on FR4 Board, t_s ≤ 10 sec.
- 2) Pulse Test: Pulse Width < 300μs, Duty Cycle ≤ 2%.
- 3) Guaranteed by design, not subject to production testing.

N- Channel Typical Characteristics

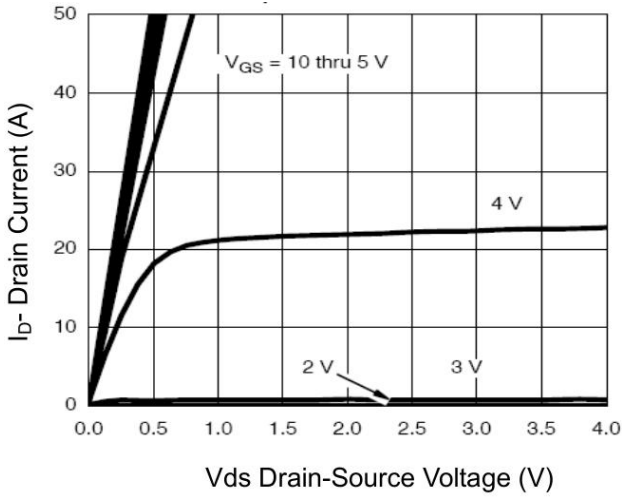


Figure 1 Output Characteristics

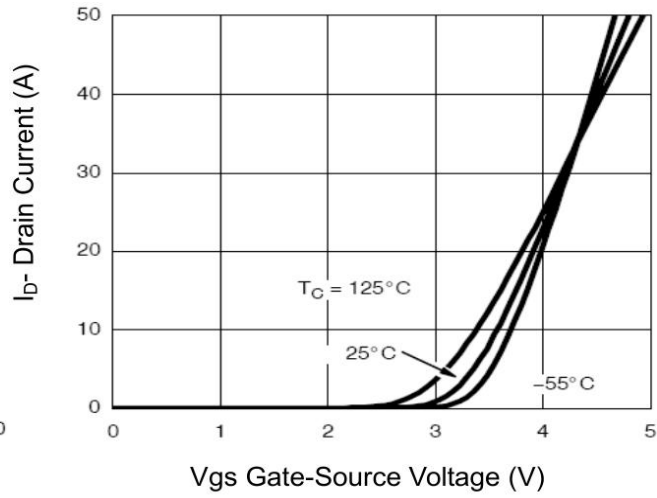


Figure 2 Transfer Characteristics

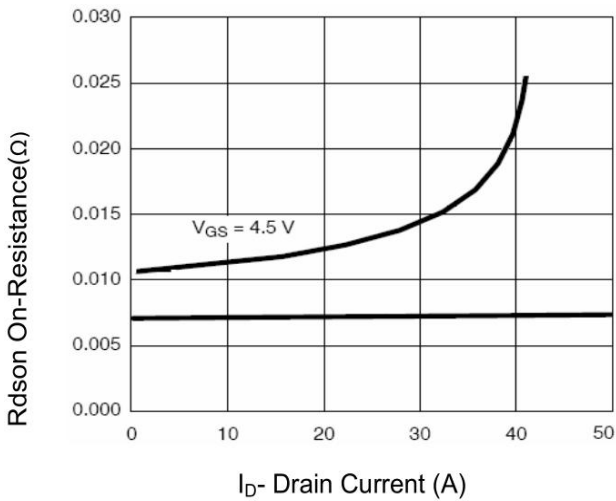


Figure 3 Rdson- Drain Current

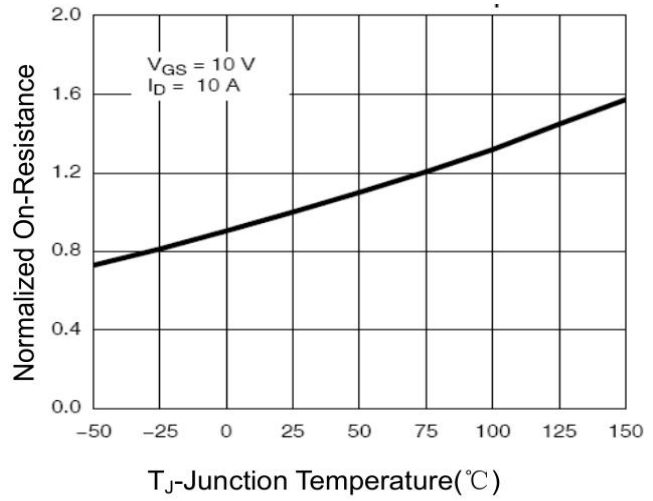


Figure 4 Rdson- Junction Temperature

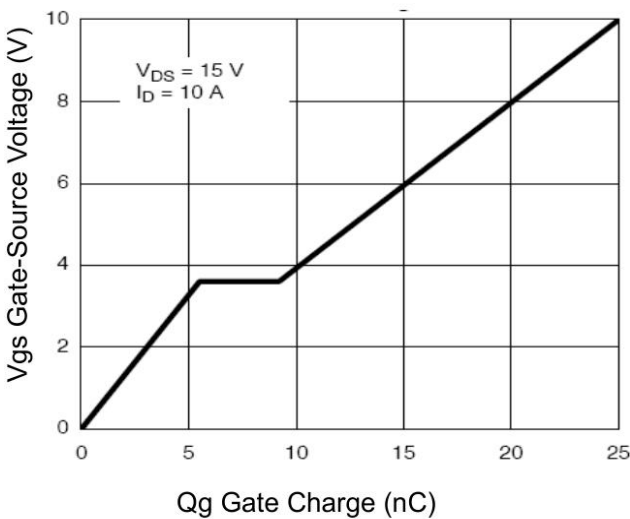


Figure 5 Gate Charge

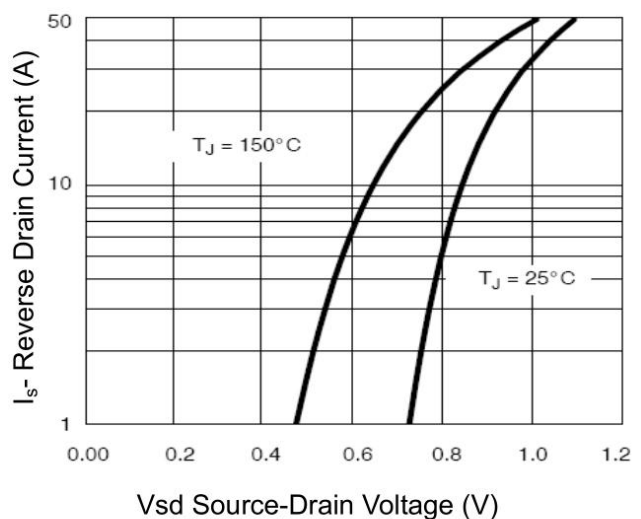


Figure 6 Source- Drain Diode Forward

N- Channel Typical Characteristics

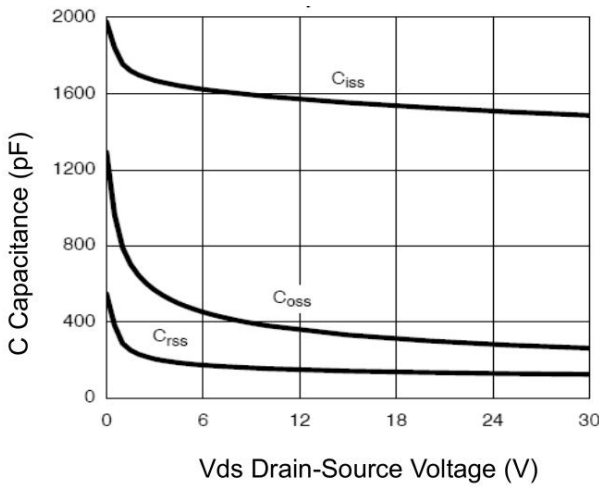


Figure 7 Capacitance vs Vds

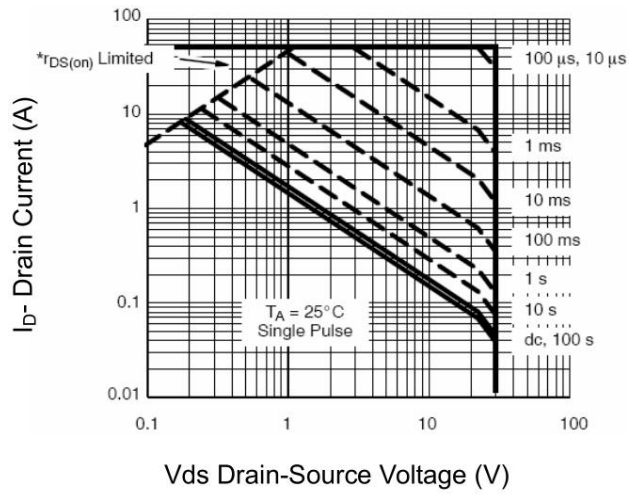


Figure 8 Safe Operation Area

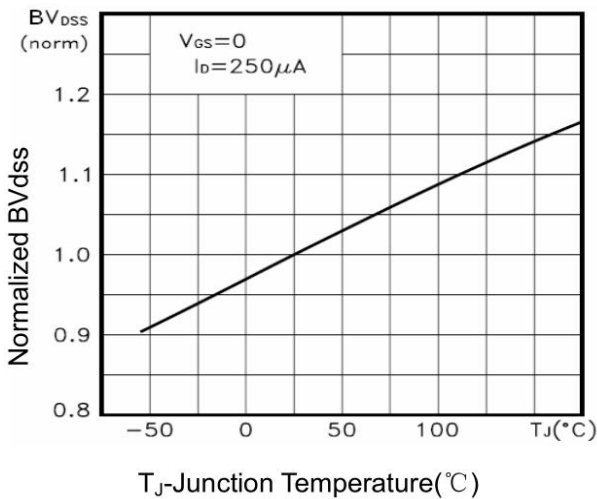


Figure 9 BV_{DSS} vs Junction Temperature

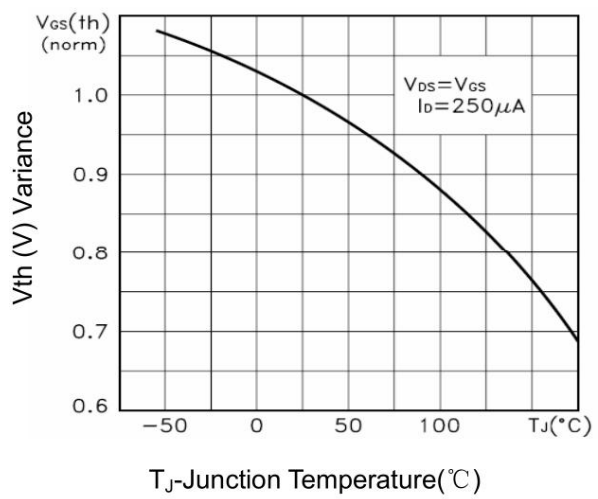


Figure 10 V_{GS(th)} vs Junction Temperature

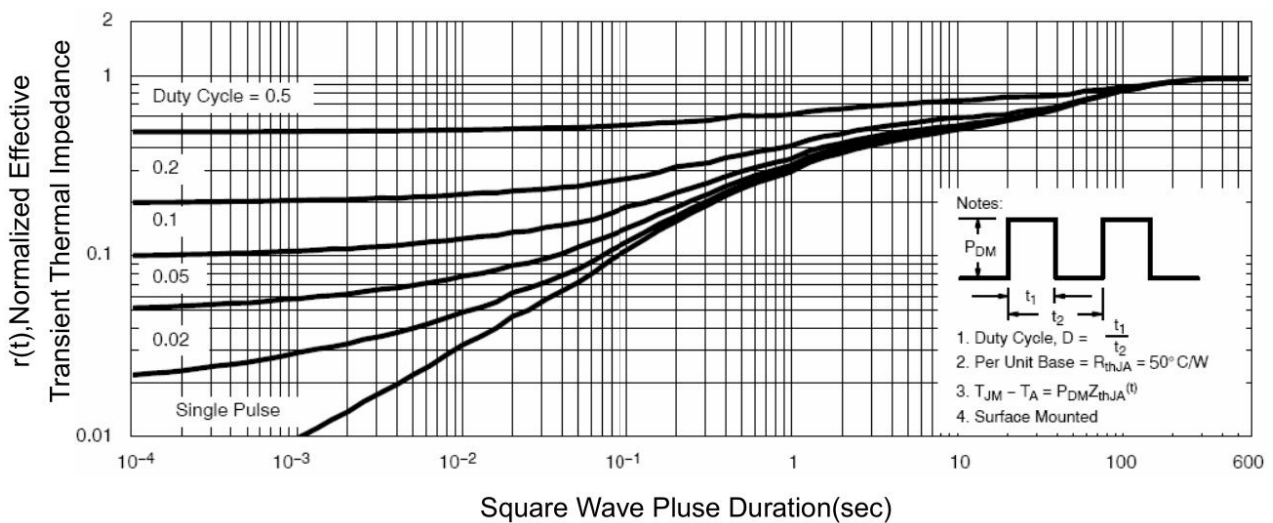


Figure 11 Normalized Maximum Transient Thermal Impedance

P- Channel Typical Characteristics

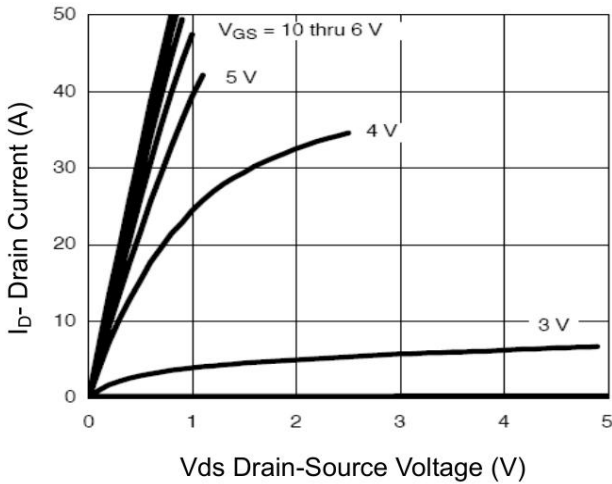


Figure 1 Output Characteristics

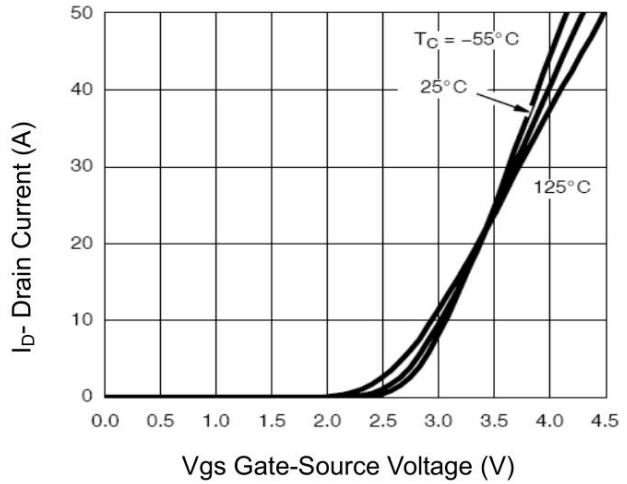


Figure 2 Transfer Characteristics

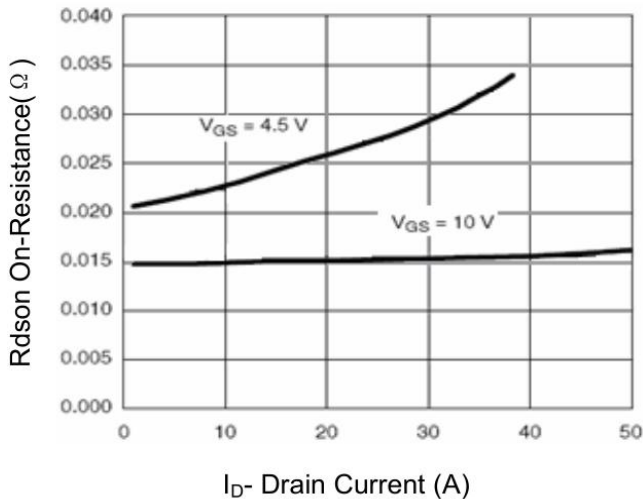


Figure 3 Drain-Source On-Resistance

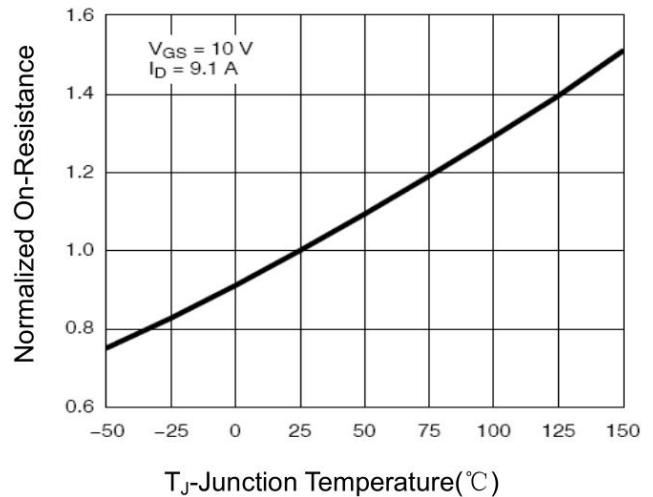


Figure 4 Drain-Source On-Resistance

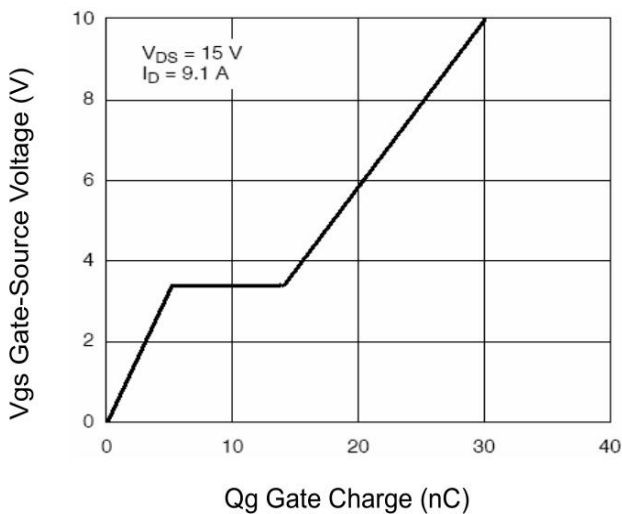


Figure 5 Gate Charge

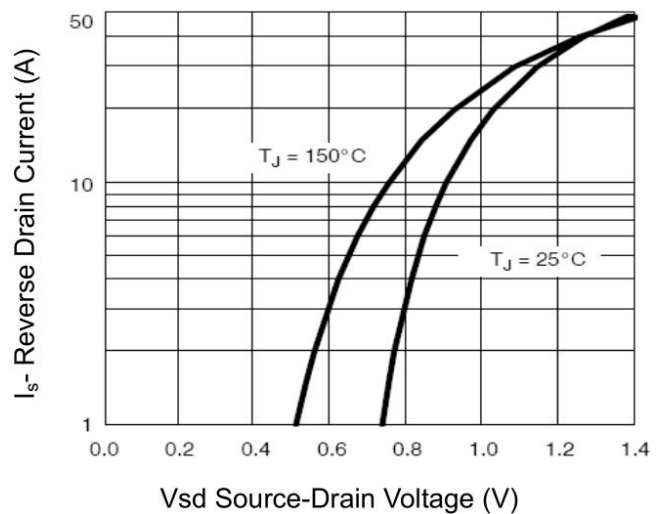
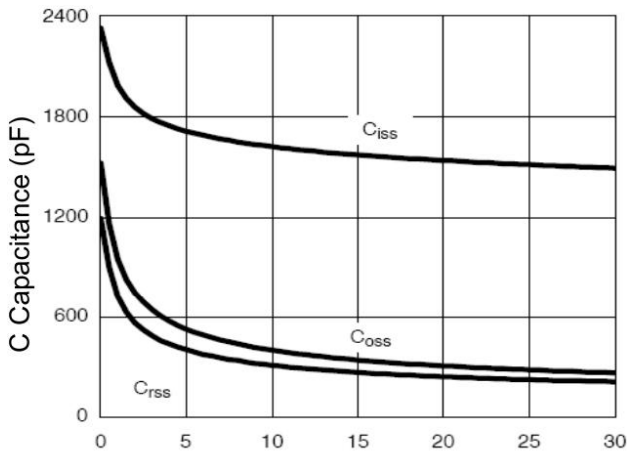
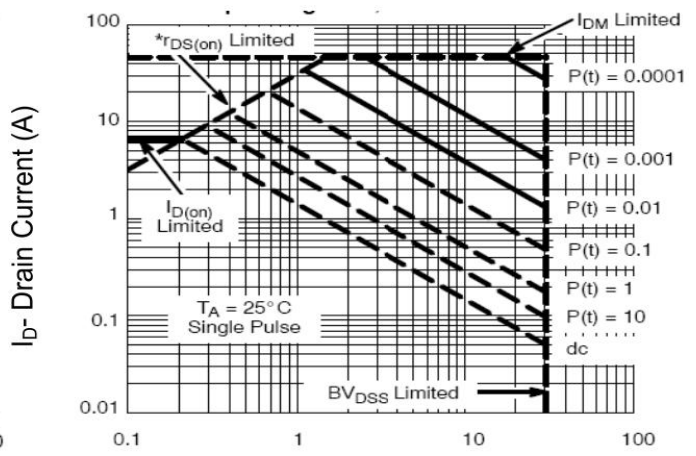


Figure 6 Source- Drain Diode Forward

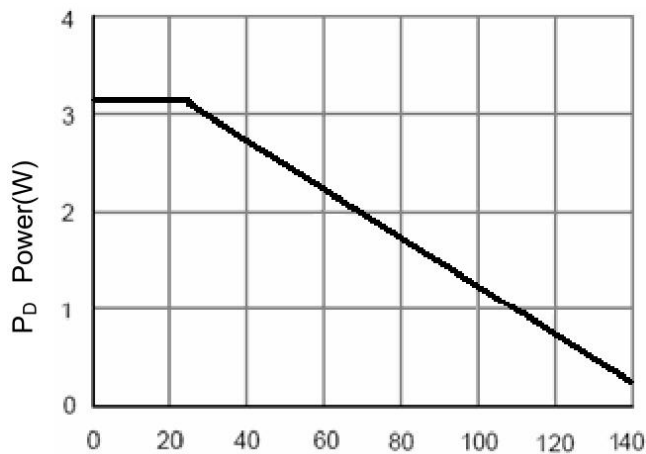
P- Channel Typical Characteristics



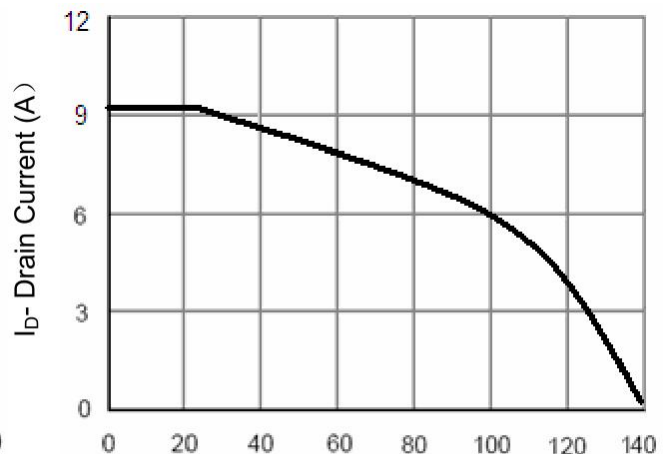
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)
Figure 9 Power Dissipation



T_J-Junction Temperature(°C)
Figure 10 Drain Current

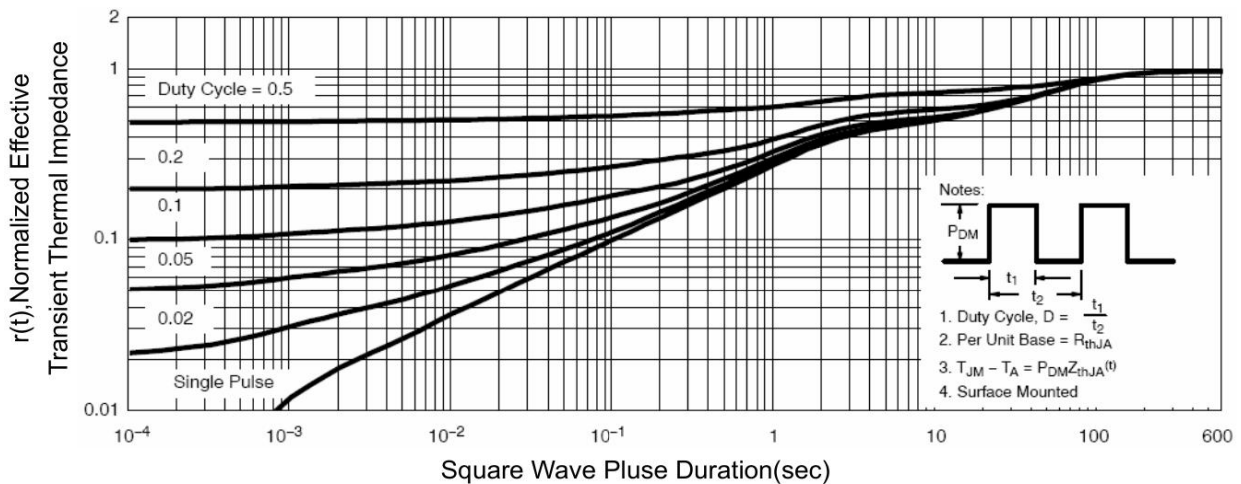
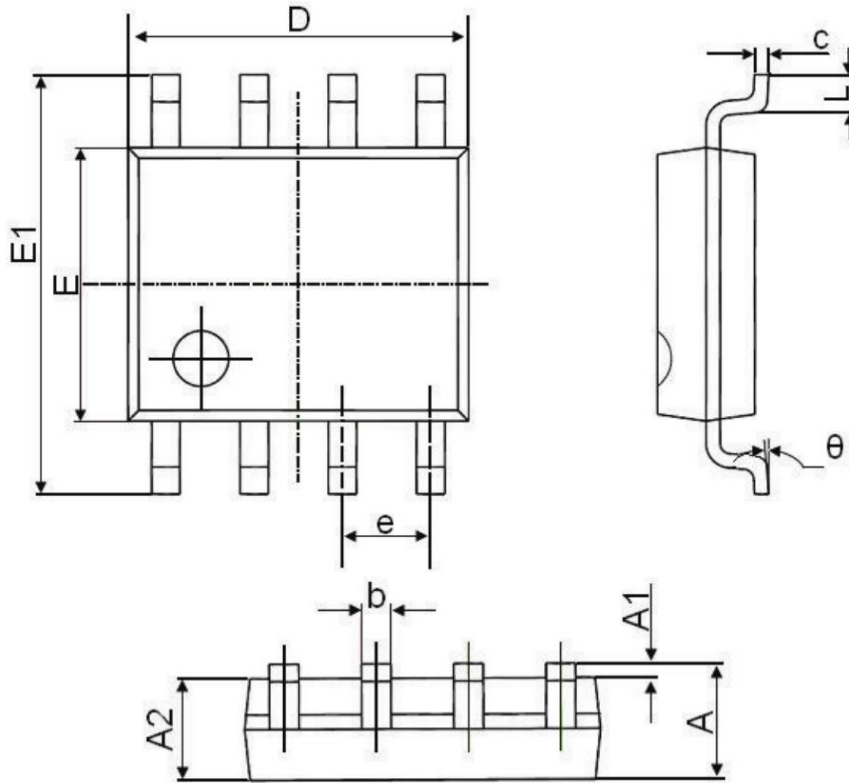


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°